

ABSTRACT OF THE DISCLOSURE

According to one aspect of the invention, a system for processing semiconductor substrates is provided. A de-gas unit may be connected to a flowing first semiconductor processing fluid to separate the first semiconductor processing fluid into second and third semiconductor processing fluids. The third semiconductor processing fluid may contain gaseous and liquid particles. A liquid trap may be connected to the de-gas unit to catch the liquid particles of the third semiconductor processing fluid. A vacuum supply may be connected to the liquid trap to draw the third semiconductor processing fluid into the liquid trap and further draw the gaseous particles out of the liquid trap.